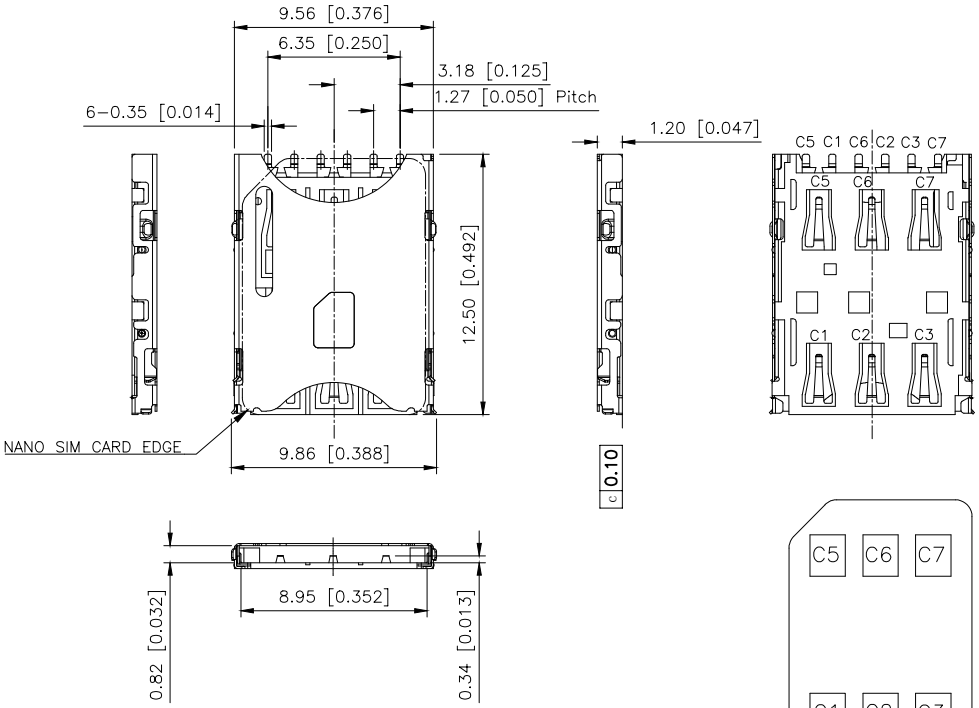
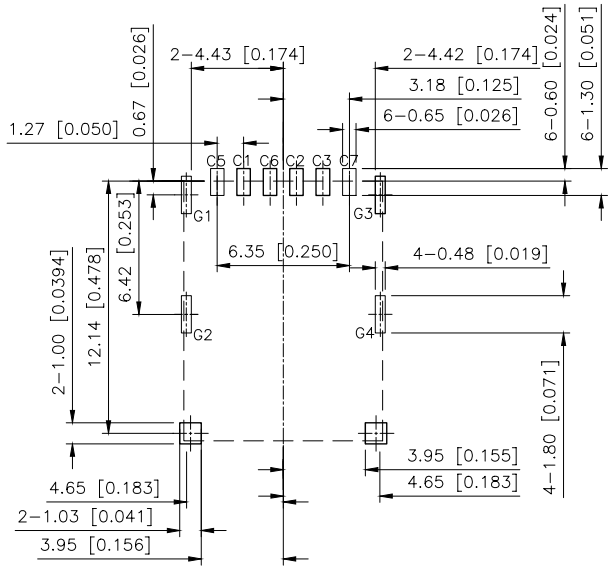
REVISIONS					
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A0	N/A		INITIAL RELEASE	/	/
A1	N/A		图面升级整理图面	2025.05.08	阿树



Nano SIM Card Pad



Recommended PCB Pattern Layout
General Tolerance:±0.05
G1−GN pin is defined as GND

Pin name	Description
C1	Vcc of SIM
C2	RST of SIM
C3	CLK of SIM
C5	GND of SIM
C6	Vpp of SIM
C7	I/O of SIM

(Connector Pin Assignments)

PLEASE CONTACT CNIMD SALES REPRESENTATIVE
TO VERIFY PRODUCT DETAILS&AVAILABILITY

1.Material/Plated 材料/电镀
1.1 Housing 胶壳:TemperatureThermoplastic,Black
1.2 Terminal 端子:CopperAlloy,Gold Flash Plated
At Contact Area And Solded Area,
Nickel Underplated Overall
1.3 Shell 外壳:Stailess steel,Nickel plated
2. Electrical Performance 电气性能
2.1 Rated Current 额定电流:1A Max.
2.2 Contact Resistance 接触电阻:100ml Max.
2.3 Insulation Resistance 绝缘电阻:500MΩ Min.
2.4 Dielectric Strength 绝缘强度:500V AC
3. Mechanical Performance 力学性能
3.1 Insertion Force 插拔力:40N Max,
3.2 Durability 耐用性:1500Cycles
4. Operating Temperature 工作温度:−25℃To+85℃

AuGLAR	±5°
X.	±0.40
X.x	±0.30
X.xx	±0.20
X.xxx	±0.15
UNSPECIFIED TOLERAuCES	

XKB 星创 Connection

DESIGN	阿树	VIEW:	MODEL TYPE: SIM CARD CONN
CHECKED		UNIT: mm/in	PART NO.: XKNANO−1412
APPROVED		SIZE: A4	DWG NO.: X−XKNANO−1412

XKB INDUSTRIAL PRECISION CO.,LIMITED

SCALE	PAGE	REVISION
N/A	1/1	A1